



# Specification

## STW8T36B

| SSC   |          | CUSTOMER |
|-------|----------|----------|
| Drawn | Approval | Approval |
|       |          |          |

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February 2013

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# STW8T36B

# STW8T36B

## 1. Description

This surface-mount LED comes in standard package dimension. It has a substrate made up of a molded plastic reflector sitting on top of a bent lead frame. The die is attached within the reflector cavity and the cavity is encapsulated by silicone.



The package design coupled with careful selection of component materials allow these products to perform with high reliability.

## Features

- White colored SMT package.
- Pb-free Reflow Soldering Application
- Suitable for all SMT assembly methods ; Suitable for all soldering methods
- RoHS Compliant

## Applications

- Interior lighting
- General lighting
- Indoor and out door displays
- Architectural / Decorative lighting

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## 2. Absolute maximum ratings [1]

| Parameter             | Symbol    | Value    | Unit |
|-----------------------|-----------|----------|------|
| Power Dissipation     | $P_d$     | 324      | mW   |
| Forward Current       | $I_F$     | 90       | mA   |
| Operating Temperature | $T_{opr}$ | -40~+85  | °C   |
| Storage Temperature   | $T_{stg}$ | -40~+100 | °C   |
| Junction Temperature  | $T_j$     | 125      | °C   |

[1] Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

\* LED's properties might be different from suggested values like above and below tables if operation condition will be exceeded our parameter range.

## 3. Electro-Optical characteristics

| Parameter                                 | Symbol          | Condition                 | Min.  | Typ. | Max.  | Unit          |
|-------------------------------------------|-----------------|---------------------------|-------|------|-------|---------------|
| Forward Voltage (per die) *               | $V_F$           | $I_F=20\text{mA}$         | 2.9   | 3.2  | 3.5   | V             |
| Reverse Current (per die)                 | $V_R$           | $V_F=5\text{V}$           | -     | -    | 10    | $\mu\text{A}$ |
| Luminous Intensity*[1]<br>(3,700~8,200 K) | $I_v$           | $I_F=60\text{mA}$         | -     | 6.3  | -     | Cd            |
| Luminous Intensity*[1]<br>(2,600~3,700 K) | $I_v$           | $I_F=60\text{mA}$         | -     | 5.5  | -     | Cd            |
| Color Correlated Temperature              | CCT             | $I_F=60\text{mA}$         | 2,600 | -    | 8,200 | K             |
| Viewing Angle [2]                         | $2\theta_{1/2}$ | $I_F=60\text{mA}$         | -     | 120  | -     | deg.          |
| Color Rendering Index*                    | $R_a$           | $I_F=60\text{mA}$         | 75    | 80   | -     | -             |
| ESD (HBM)                                 |                 | 1.5k $\Omega$ ; 100p<br>F | 1     | -    | -     | KV            |
| Thermal resistance [3]                    | $R_{thJP}$      | $I_F=60\text{mA}$         |       | 22   |       | °C/W          |

[1] The luminous intensity  $I_V$  was measured at the peak of the spatial pattern which may not be aligned with the mechanical axis of the LED package.

[2]  $2\theta_{1/2}$  is the off-axis where the luminous intensity is 1/2 of the peak intensity.

[3] Thermal resistance:  $R_{thJS}$  (Junction / solder)

\* Tolerance :  $V_F : \pm 0.1\text{V}$ ,  $I_V : \pm 10\%$ ,  $R_a : \pm 3$ ,  $x, y : \pm 0.01$

[Note] All measurements were made under the standardized environment of SSC.

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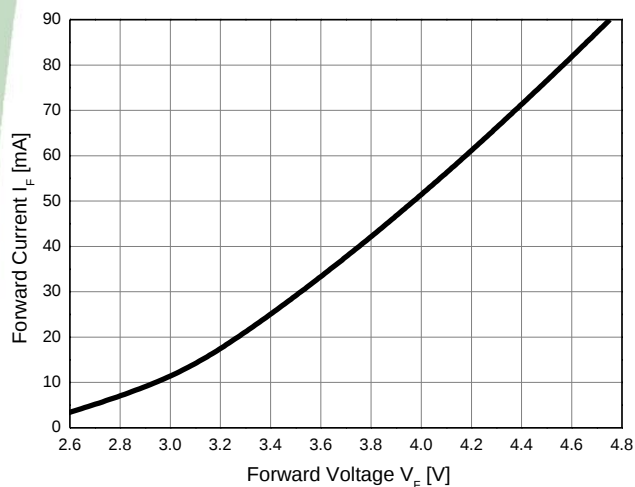
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## 4. Optical characteristics

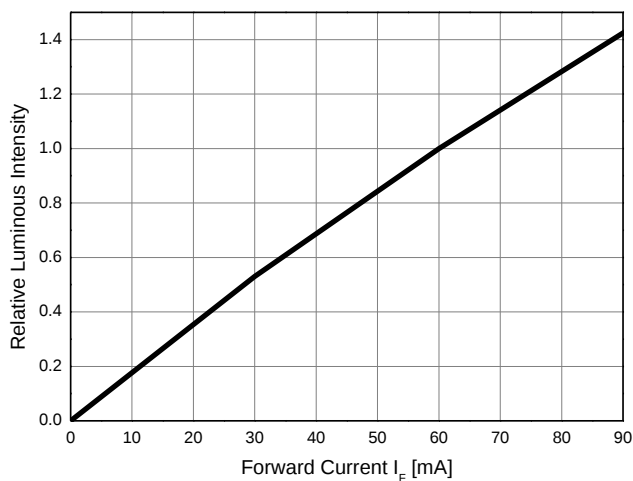
Forward Voltage  
vs. Forward Current (Per die)

$T_a = 25^\circ\text{C}$

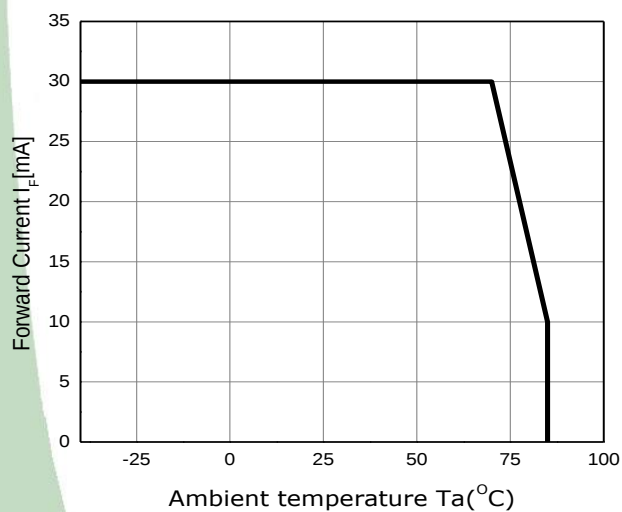


Forward Current  
vs. Relative Luminous Intensity

$T_a = 25^\circ\text{C}$

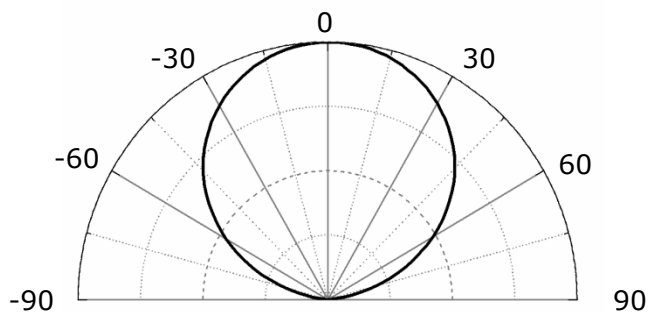


Ambient Temperature  
vs. Maximum Forward Current (per die)



Directivity

$T_a = 25^\circ\text{C}$



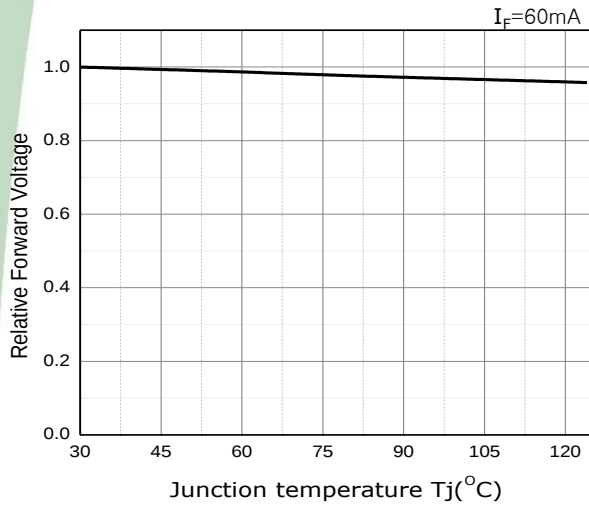
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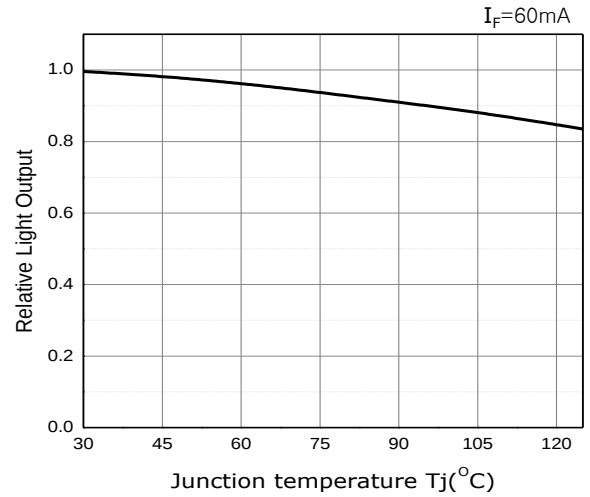
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## 4. Optical characteristics

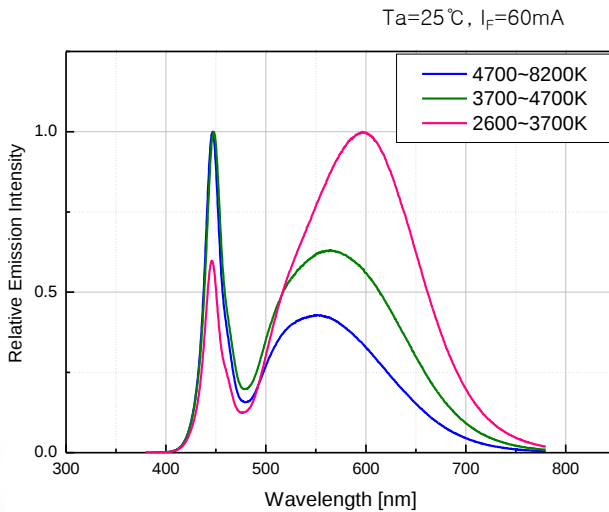
Forward Voltage Shift  
vs. Junction Temperature



Relative Light Output  
vs. Junction Temperature



Spectrum



## 5. Reliability Test

| Item                                     | Reference          | Test Conditions                                                                  | Duration / Cycle | Number of Damaged |
|------------------------------------------|--------------------|----------------------------------------------------------------------------------|------------------|-------------------|
| Thermal Shock                            | EIAJ<br>ED-4701    | $T_a = -40^{\circ}\text{C}(30\text{min}) \sim 100^{\circ}\text{C}(30\text{min})$ | 100 Cycle        | 0/22              |
| High Temperature Storage                 | EIAJ<br>ED-4701    | $T_a = 100^{\circ}\text{C}$                                                      | 1000 Hours       | 0/22              |
| High Temp. High Humidity Storage         | EIAJ<br>ED-4701    | $T_a = 60^{\circ}\text{C}$ , RH=90%                                              | 1000 Hours       | 0/22              |
| Low Temperature Storage                  | EIAJ<br>ED-4701    | $T_a = -40^{\circ}\text{C}$                                                      | 1000 Hours       | 0/22              |
| Operating Endurance Test                 | Internal Reference | $T_a = 25^{\circ}\text{C}$ , $I_F = 60\text{mA}$                                 | 1000 Hours       | 0/22              |
| High Temperature High Humidity Life Test | Internal Reference | $T_a = 60^{\circ}\text{C}$ , RH=90%, $I_F = 60\text{mA}$                         | 500 Hours        | 0/22              |
| High Temperature Life Test               | Internal Reference | $T_a = 85^{\circ}\text{C}$ , $I_F = 60\text{mA}$                                 | 500 Hours        | 0/22              |
| Low Temperature Life Test                | Internal Reference | $T_a = -40^{\circ}\text{C}$ , $I_F = 60\text{mA}$                                | 1000 Hours       | 0/22              |
| ESD(HBM)                                 | MIL-STD-883D       | 1KV at 1.5k $\Omega$ ; 100pF                                                     | 3 Time           | 0/22              |
| Reflow                                   | $T_{sol}$          | 260 $^{\circ}\text{C} < 10\text{sec}$ . Reflow Soldering                         | 3 Time           | 0/22              |

### □ CRITERIA FOR JUDGING THE DAMAGE

| Item               | Symbol | Condition           | Criteria for Judgment           |                                 |
|--------------------|--------|---------------------|---------------------------------|---------------------------------|
|                    |        |                     | MIN                             | MAX                             |
| Forward Voltage    | $V_F$  | $I_F = 60\text{mA}$ | -                               | USL <sup>[1]</sup> $\times$ 1.2 |
| Luminous Intensity | $I_V$  | $I_F = 60\text{mA}$ | LSL <sup>[2]</sup> $\times$ 0.7 | -                               |

Note : [1] USL : Upper Standard Level

[2] LSL : Lower Standard Level

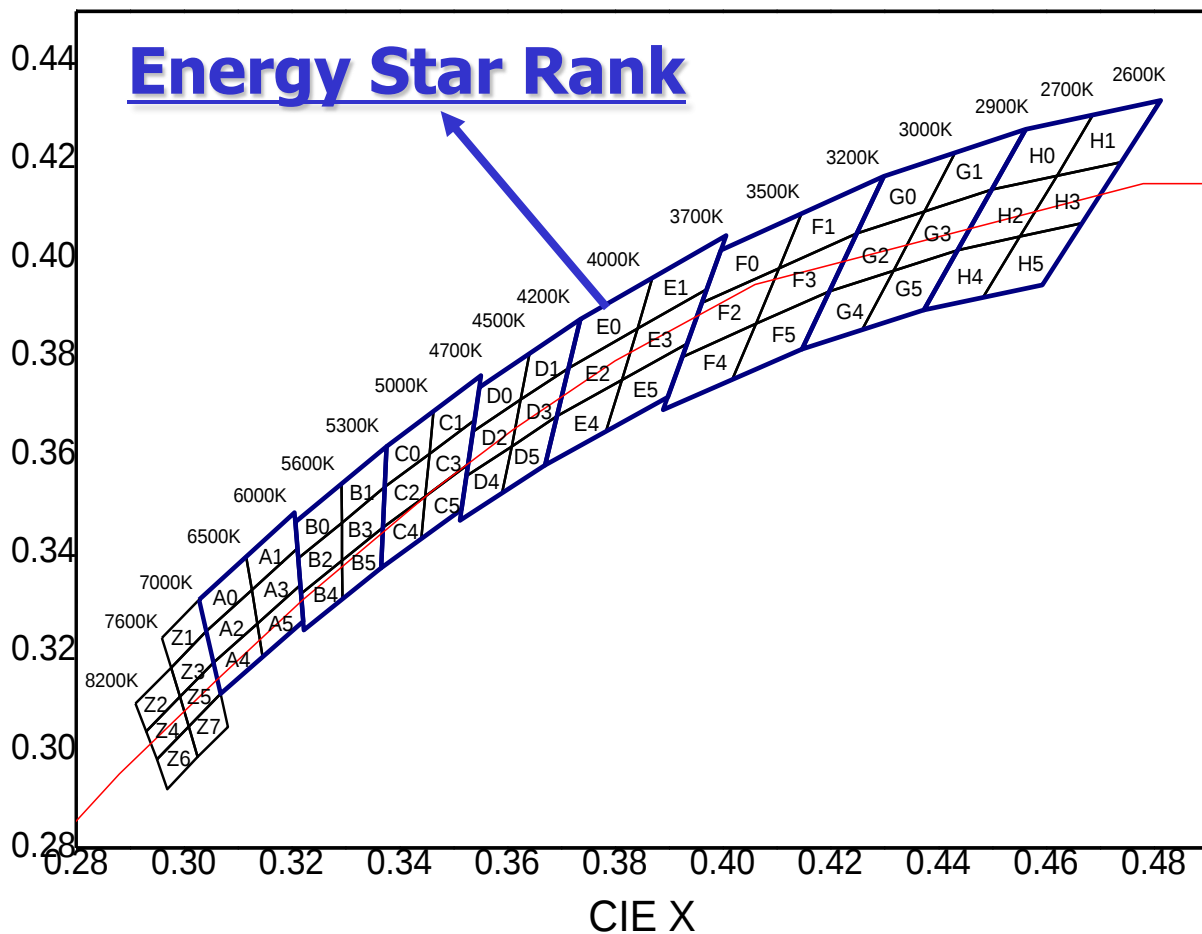
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## 6. Color & Binning

CIE Y



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## 6. Color & Binning

### ● COLOR RANK

<IF=60mA, Ta=25℃>

| <b>Z1</b> |        | <b>Z2</b> |        | <b>Z3</b> |        |
|-----------|--------|-----------|--------|-----------|--------|
| CIE X     | CIE Y  | CIE X     | CIE Y  | CIE X     | CIE Y  |
| 0.2959    | 0.3227 | 0.291     | 0.3093 | 0.2976    | 0.3166 |
| 0.2976    | 0.3166 | 0.293     | 0.3037 | 0.2993    | 0.3107 |
| 0.3041    | 0.324  | 0.2993    | 0.3107 | 0.3055    | 0.3177 |
| 0.3028    | 0.3304 | 0.2976    | 0.3166 | 0.3041    | 0.324  |
| <b>Z4</b> |        | <b>Z5</b> |        | <b>Z6</b> |        |
| CIE X     | CIE Y  | CIE X     | CIE Y  | CIE X     | CIE Y  |
| 0.293     | 0.3037 | 0.2993    | 0.3107 | 0.295     | 0.298  |
| 0.295     | 0.298  | 0.3009    | 0.3047 | 0.2969    | 0.2919 |
| 0.3009    | 0.3047 | 0.3068    | 0.3113 | 0.3025    | 0.2985 |
| 0.2993    | 0.3107 | 0.3055    | 0.3177 | 0.3009    | 0.3047 |
| <b>Z7</b> |        |           |        |           |        |
| CIE X     | CIE Y  |           |        |           |        |
| 0.3009    | 0.3047 |           |        |           |        |
| 0.3025    | 0.2985 |           |        |           |        |
| 0.3082    | 0.3046 |           |        |           |        |
| 0.3068    | 0.3113 |           |        |           |        |

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\* Measurement Uncertainty of the Color Coordinates :  $\pm 0.01$

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## 6. Color & Binning

### ● COLOR RANK

&lt;IF=60mA, Ta=25℃&gt;

| A0     |        | A1     |        | A2     |        |
|--------|--------|--------|--------|--------|--------|
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3028 | 0.3304 | 0.3115 | 0.3393 | 0.3041 | 0.324  |
| 0.3041 | 0.324  | 0.3126 | 0.3324 | 0.3055 | 0.3177 |
| 0.3126 | 0.3324 | 0.321  | 0.3408 | 0.3136 | 0.3256 |
| 0.3115 | 0.3393 | 0.3205 | 0.3481 | 0.3126 | 0.3324 |
| A3     |        | A4     |        | A5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3126 | 0.3324 | 0.3055 | 0.3177 | 0.3136 | 0.3256 |
| 0.3136 | 0.3256 | 0.3068 | 0.3113 | 0.3146 | 0.3187 |
| 0.3216 | 0.3334 | 0.3146 | 0.3187 | 0.3221 | 0.3261 |
| 0.321  | 0.3408 | 0.3136 | 0.3256 | 0.3216 | 0.3334 |
| B0     |        | B1     |        | B2     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3207 | 0.3462 | 0.3292 | 0.3539 | 0.3212 | 0.3389 |
| 0.3212 | 0.3389 | 0.3293 | 0.3461 | 0.3217 | 0.3316 |
| 0.3293 | 0.3461 | 0.3373 | 0.3534 | 0.3293 | 0.3384 |
| 0.3292 | 0.3539 | 0.3376 | 0.3616 | 0.3293 | 0.3461 |
| B3     |        | B4     |        | B5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3293 | 0.3461 | 0.3217 | 0.3316 | 0.3293 | 0.3384 |
| 0.3293 | 0.3384 | 0.3222 | 0.3243 | 0.3294 | 0.3306 |
| 0.3369 | 0.3451 | 0.3294 | 0.3306 | 0.3366 | 0.3369 |
| 0.3373 | 0.3534 | 0.3293 | 0.3384 | 0.3369 | 0.3451 |

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## 6. Color & Binning

### ● COLOR RANK

&lt;IF=60mA, Ta=25℃&gt;

| C0     |        | C1     |        | C2     |        |
|--------|--------|--------|--------|--------|--------|
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3376 | 0.3616 | 0.3463 | 0.3687 | 0.3373 | 0.3534 |
| 0.3373 | 0.3534 | 0.3456 | 0.3601 | 0.3369 | 0.3451 |
| 0.3456 | 0.3601 | 0.3539 | 0.3669 | 0.3448 | 0.3514 |
| 0.3463 | 0.3687 | 0.3552 | 0.376  | 0.3456 | 0.3601 |
| C3     |        | C4     |        | C5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3456 | 0.3601 | 0.3369 | 0.3451 | 0.3448 | 0.3514 |
| 0.3448 | 0.3514 | 0.3366 | 0.3369 | 0.344  | 0.3428 |
| 0.3526 | 0.3578 | 0.344  | 0.3428 | 0.3514 | 0.3487 |
| 0.3539 | 0.3669 | 0.3448 | 0.3514 | 0.3526 | 0.3578 |
| D0     |        | D1     |        | D2     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3548 | 0.3736 | 0.3641 | 0.3804 | 0.3536 | 0.3646 |
| 0.3536 | 0.3646 | 0.3625 | 0.3711 | 0.3523 | 0.3555 |
| 0.3625 | 0.3711 | 0.3714 | 0.3775 | 0.3608 | 0.3616 |
| 0.3641 | 0.3804 | 0.3736 | 0.3874 | 0.3625 | 0.3711 |
| D3     |        | D4     |        | D5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3625 | 0.3711 | 0.3523 | 0.3555 | 0.3608 | 0.3616 |
| 0.3608 | 0.3616 | 0.3511 | 0.3465 | 0.359  | 0.3521 |
| 0.3692 | 0.3677 | 0.359  | 0.3521 | 0.367  | 0.3578 |
| 0.3714 | 0.3775 | 0.3608 | 0.3616 | 0.3692 | 0.3677 |

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## 6. Color & Binning

### ● COLOR RANK

&lt;IF=60mA, Ta=25℃&gt;

| E0     |        | E1     |        | E2     |        |
|--------|--------|--------|--------|--------|--------|
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3736 | 0.3874 | 0.3869 | 0.3958 | 0.3714 | 0.3775 |
| 0.3714 | 0.3775 | 0.3842 | 0.3855 | 0.3692 | 0.3677 |
| 0.3842 | 0.3855 | 0.397  | 0.3935 | 0.3813 | 0.3751 |
| 0.3869 | 0.3958 | 0.4006 | 0.4044 | 0.3842 | 0.3855 |
| E3     |        | E4     |        | E5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3842 | 0.3855 | 0.3692 | 0.3677 | 0.3813 | 0.3751 |
| 0.3813 | 0.3751 | 0.367  | 0.3578 | 0.3783 | 0.3646 |
| 0.3934 | 0.3825 | 0.3783 | 0.3646 | 0.3898 | 0.3716 |
| 0.397  | 0.3935 | 0.3813 | 0.3751 | 0.3934 | 0.3825 |
| F0     |        | F1     |        | F2     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.3996 | 0.4015 | 0.4146 | 0.4089 | 0.396  | 0.3907 |
| 0.396  | 0.3907 | 0.4104 | 0.3978 | 0.3925 | 0.3798 |
| 0.4104 | 0.3978 | 0.4248 | 0.4048 | 0.4062 | 0.3865 |
| 0.4146 | 0.4089 | 0.4299 | 0.4165 | 0.4104 | 0.3978 |
| F3     |        | F4     |        | F5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.4104 | 0.3978 | 0.3925 | 0.3798 | 0.4062 | 0.3865 |
| 0.4062 | 0.3865 | 0.3889 | 0.369  | 0.4017 | 0.3751 |
| 0.4198 | 0.3931 | 0.4017 | 0.3751 | 0.4147 | 0.3814 |
| 0.4248 | 0.4048 | 0.4062 | 0.3865 | 0.4198 | 0.3931 |

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\* Measurement Uncertainty of the Color Coordinates :  $\pm 0.01$ 

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## 6. Color & Binning

### ● COLOR RANK

&lt;IF=60mA, Ta=25℃&gt;

| G0     |        | G1     |        | G2     |        |
|--------|--------|--------|--------|--------|--------|
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.4299 | 0.4165 | 0.443  | 0.4212 | 0.4248 | 0.4048 |
| 0.4248 | 0.4048 | 0.4374 | 0.4093 | 0.4198 | 0.3931 |
| 0.4374 | 0.4093 | 0.4499 | 0.4138 | 0.4317 | 0.3973 |
| 0.443  | 0.4212 | 0.4562 | 0.426  | 0.4374 | 0.4093 |
| G3     |        | G4     |        | G5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.4374 | 0.4093 | 0.4198 | 0.3931 | 0.4317 | 0.3973 |
| 0.4317 | 0.3973 | 0.4147 | 0.3814 | 0.4259 | 0.3853 |
| 0.4436 | 0.4015 | 0.4259 | 0.3853 | 0.4373 | 0.3893 |
| 0.4499 | 0.4138 | 0.4317 | 0.3973 | 0.4436 | 0.4015 |
| H0     |        | H1     |        | H2     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.4562 | 0.426  | 0.4687 | 0.4289 | 0.4499 | 0.4138 |
| 0.4499 | 0.4138 | 0.462  | 0.4166 | 0.4436 | 0.4015 |
| 0.462  | 0.4166 | 0.474  | 0.4194 | 0.4551 | 0.4042 |
| 0.4687 | 0.4289 | 0.481  | 0.4319 | 0.462  | 0.4166 |
| H3     |        | H4     |        | H5     |        |
| CIE X  | CIE Y  | CIE X  | CIE Y  | CIE X  | CIE Y  |
| 0.462  | 0.4166 | 0.4436 | 0.4015 | 0.4551 | 0.4042 |
| 0.4551 | 0.4042 | 0.4373 | 0.3893 | 0.4483 | 0.3919 |
| 0.4666 | 0.4069 | 0.4483 | 0.3919 | 0.4593 | 0.3944 |
| 0.474  | 0.4194 | 0.4551 | 0.4042 | 0.4666 | 0.4069 |

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\* Measurement Uncertainty of the Color Coordinates :  $\pm 0.01$ 

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## 7. Bin Code Description

| Bin Code                 |            |                     |
|--------------------------|------------|---------------------|
| Luminous Intensity [mcd] | Color Rank | Forward Voltage [V] |
| N5                       | A1         | Z3                  |



2,600K ~ 8,200K

| Luminous Intensity [mcd]<br>@ $I_F = 60\text{mA}$ |       |       | FLUX<br>[lm] |
|---------------------------------------------------|-------|-------|--------------|
| RANK                                              | Min.  | Max.  | Typ.         |
| N0                                                | 5,000 | 5,500 | 16.0         |
| N5                                                | 5,500 | 6,000 | 17.2         |
| P0                                                | 6,000 | 6,500 | 18.5         |
| P5                                                | 6,500 | 7,000 | 19.7         |
| Q0                                                | 7,000 | 7,500 | 21.2         |
| Q5                                                | 7,500 | 8,000 | 22.6         |

| Color Rank<br>@ $I_F = 60\text{mA}$ |
|-------------------------------------|
| Z~H                                 |

| Average for Total<br>Forward Voltage [V]<br>@ $I_F = 60\text{mA}$ |      |      |
|-------------------------------------------------------------------|------|------|
| RANK                                                              | Min. | Max. |
| Y3                                                                | 2.9  | 3.0  |
| Z1                                                                | 3.0  | 3.1  |
| Z2                                                                | 3.1  | 3.2  |
| Z3                                                                | 3.2  | 3.3  |
| A1                                                                | 3.3  | 3.4  |
| A2                                                                | 3.4  | 3.5  |



Available ranks



Not yet available ranks

| CCT         | IV Rank |    |    |    |    |    |
|-------------|---------|----|----|----|----|----|
| 3700~8200 K | N0      | N5 | P0 | P5 | Q0 | Q5 |
| 2600~3700 K | N0      | N5 | P0 | P5 | Q0 | Q5 |

[Note] All measurements were made under the standardized environment of SSC.

In order to ensure availability, single color rank will not be orderable.

[1] Classification criteria : Luminous intensity IV

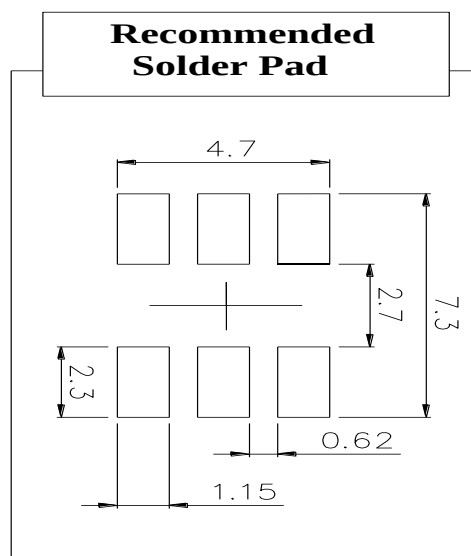
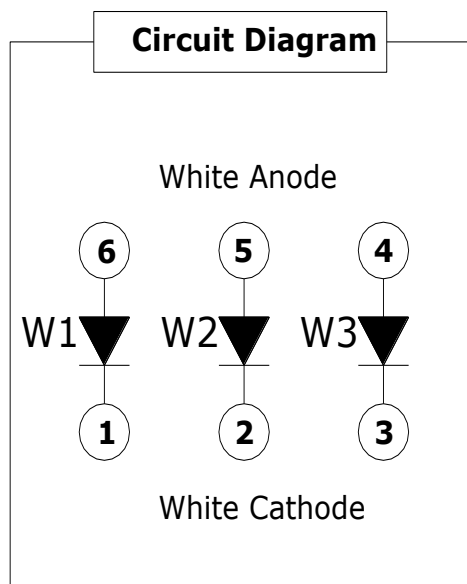
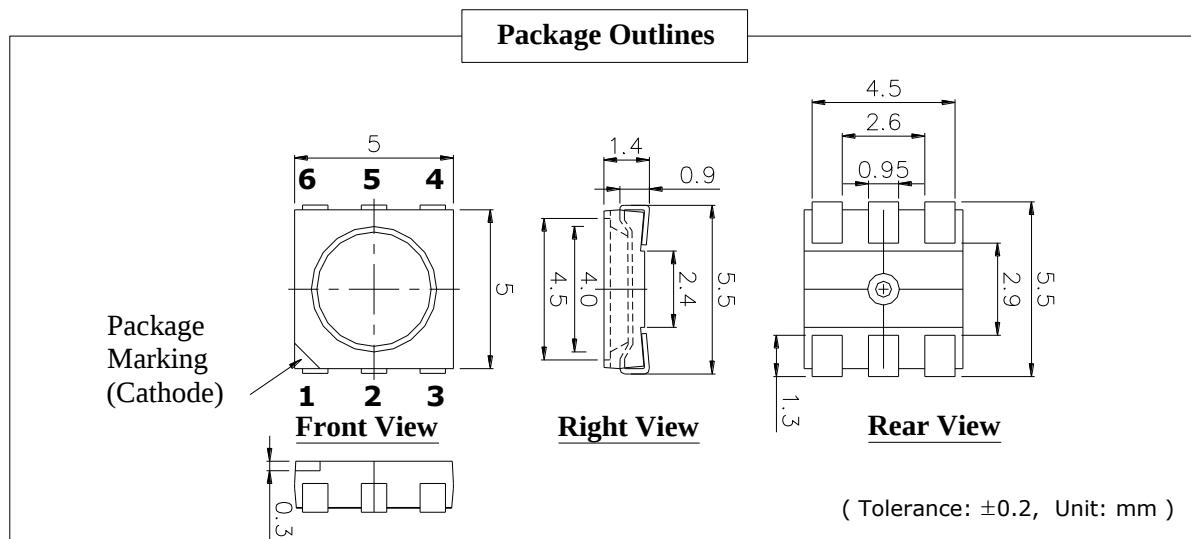
[2] Please use for only reference.

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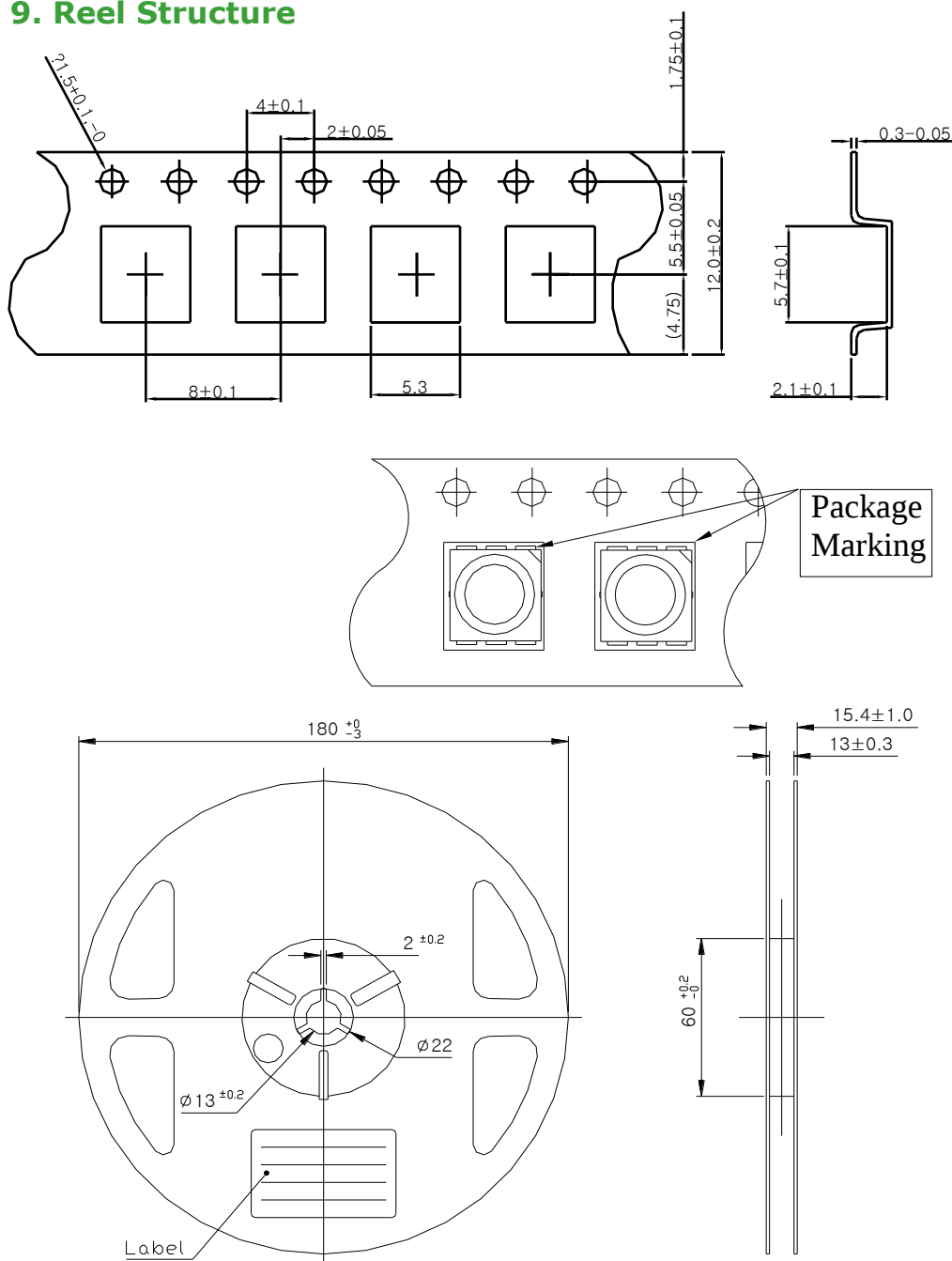
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## 8.Outline Dimension



## 9. Reel Structure



( Tolerance:  $\pm 0.2$ , Unit: mm )

- 1)Quantity : 1,200pcs/Reel
- 2)Cumulative Tolerance : Cumulative Tolerance/10 pitches to be  $\pm 0.2$ mm
- 3)Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10 to the carrier tape
- 4)Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

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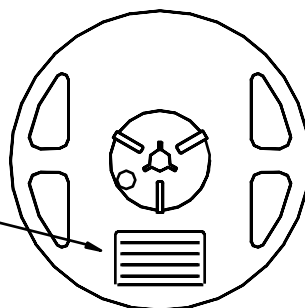
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## 10. Packing

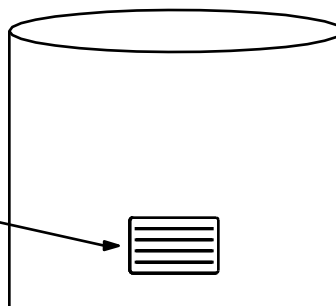
### Reel

RANK: XXX  
 QUANTITY : XXXX  
 LOT NUMBER : XXXXXXXXXXXX  
 PART NUMBER : XXXXXXXX  
 SEOUL SEMICONDUCTOR CO., LTD.



### Aluminum Vinyl Bag

RANK: XXX  
 QUANTITY : XXXX  
 LOT NUMBER : XXXXXXXXXXXX  
 PART NUMBER : XXXXXXXX  
 SEOUL SEMICONDUCTOR CO., LTD.



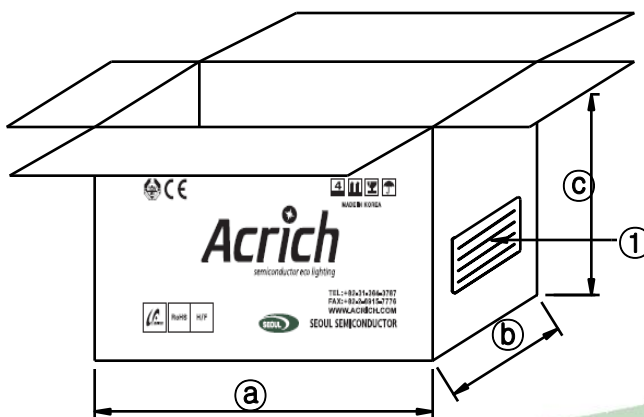
### Outer Box Structure

Material : Paper(SW3B(B))

| TYPE  | SIZE (mm) |     |     |
|-------|-----------|-----|-----|
|       | (a)       | (b) | (c) |
| 7inch | 245       | 220 | 102 |
|       | 245       | 220 | 142 |

#### ① SIDE

RANK: XXX  
 QUANTITY : XXXX  
 LOT NUMBER : XXXXXXXXXXXX  
 PART NUMBER : XXXXXXXX  
 SEOUL SEMICONDUCTOR CO., LTD.



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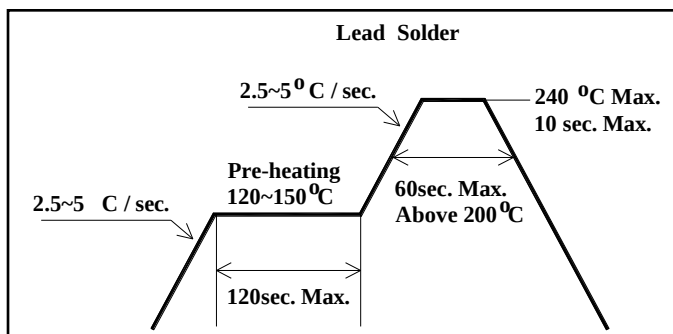
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## 11. Soldering

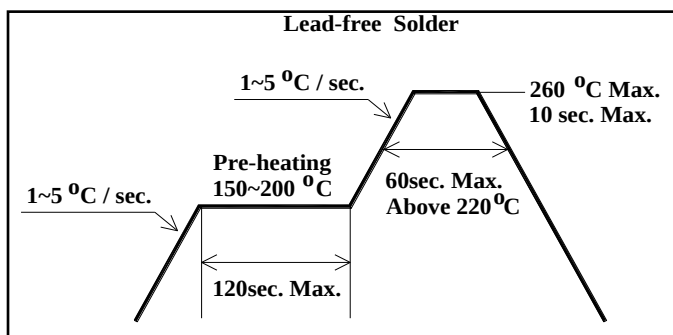
### (1) Lead Solder

| Lead Solder              |               |
|--------------------------|---------------|
| Pre-heat                 | 120~150℃      |
| Pre-heat time            | 120 sec. Max. |
| Peak-Temperature         | 240℃ Max.     |
| Soldering time Condition | 10 sec. Max.  |



### (2) Lead-Free Solder

| Lead Free Solder         |               |
|--------------------------|---------------|
| Pre-heat                 | 150~200℃      |
| Pre-heat time            | 120 sec. Max. |
| Peak-Temperature         | 260℃ Max.     |
| Soldering time Condition | 10 sec. Max.  |



### (3) Hand Soldering conditions

Do not exceed 4 seconds at maximum 315°C under soldering iron.

### (4) The encapsulated material of the LEDs is silicone.

Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the chip mounter, the picking up nozzle that does not affect the silicone resin should be used.

### (5) It is recommended that the customer use the nitrogen reflow method.

### (6) Repairing should not be done after the LEDs have been soldered.

### (7) Reflow soldering should not be done more than two times.

In the case of more than 24 hours passed soldering after first, LEDs will be damaged.

[Note] In case that the soldered products are reused in soldering process, we don't guarantee the products.

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## 12. Precaution for use

### 1) Storage

In order to avoid the absorption of moisture, it is recommended to store in a dry box (or a desiccator) with a desiccant. Otherwise, to store them in the following environment is recommended.

Temperature : 5°C ~30°C Humidity : maximum 70%RH

### 2) Attention after open.

LED is correspond to SMD, when LED be soldered dip, interfacial separation may affect the light transmission efficiency, causing the light intensity to drop. Attention in followed;

a. After opened and mounted the soldering shall be quickly.

b. Keeping of a fraction

Temperature : 5 ~ 40°C Humidity : less than 30%

3) In the case of more than 1 week passed after opening or change color of indicator on desiccant, components shall be dried 10-12hr. at 60±5°C.

4) Silver plating might be tarnished in the environment that contains corrosive gases and materials. Also any product that has tarnished lead might be decreased the solder-ability and optical-electrical properties compare to normal ones.

Please do not expose the product in the corrosive environment during the storage.

5) Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.

6) Quick cooling shall be avoided.

7) Components shall not be mounted on warped direction of PCB.

8) Anti radioactive ray design is not considered for the products.

9) This device should not be used in any type of fluid such as water, oil, organic solvent etc. When washing is required, IPA should be used.

10) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.

11) The LEDs must be soldered within seven days after opening the moisture-proof packing.

12) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.

13) The appearance and specifications of the product may be modified for improvement without notice.

14) Please note the information contained herein is subject to change.

SSC reserves the right to modify or change the design of LED package inside structure without prior notice unless optical performance changes.

15) We recommend using solder paste composed of AgCuSn, because pastes that contain Bi or B might cause color change of Ag during surface mount technology.

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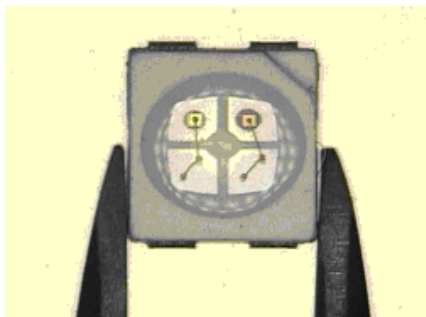
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### 13. Handling of Silicone Resin LEDs

- 1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.



- 2) In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.



- 3) When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

- 4) Silicone differs from materials conventionally used for the manufacturing of LEDs. These conditions must be considered during the handling of such devices. Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust.

As mentioned previously, the increased sensitivity to dust requires special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components.

- 5) SSC suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

- 6) Please do not mold this product into another resin (epoxy, urethane, etc) and do not handle this product with acid or sulfur material in sealed space.

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.